Spec. No.: RLP-K-HTS-0001 /12

Date: 2022. 12. 31

Data sheet

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

Style: RLP16,20,32,63, MLP20,63

RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: •Stock conditions

Temperature: $+5^{\circ}C \sim +35^{\circ}C$ Relative humidity: $25\% \sim 75\%$

The period of guarantee: Within 2 year from shipment by the company.

Solderability shall be satisfied.

- Product specification contained in this data sheet are subject to change at any time without notice
- •If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

/12

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 1/19

1. Scope

1.1 This data sheet covers the detail requirements for metal-plate chip resistor; low ohm, style of RLP16, 20, 32, 63, MLP20, 63.

Style

1.2 Applicable documents

JIS C 5201-1: 2011, JIS C 5201-8: 2014, JIS C 5201-8-1: 2014 IEC60115-1: 2008, IEC60115-8: 2009, IEC60115-8-1: 2014

2. Classification

Type designation shall be the following form.

(Example)

RLP	63	K	R010	F	TE
1	2	3	4	5	6
Sty	/le				

1 Metal - plate chip resistor; low ohm

2 Size

RLP16	1608 size, 0.33W
RLP20	2012 size, 0.5W
RLP32	3216 size, 1W
RLP63	6332 size, 1W
MLP20	2012 size, 1W
MLP63	6332 size, 2W

3 Temperature coefficient of resistance

N	±70×10 ⁻⁶ / °C
K	±100×10 ⁻⁶ / °C
(Doob)	±150×10 ⁻⁶ / °C
–(Dash)	±250×10 ⁻⁶ / °C

4 Rated resistance

1L50	1.5mΩ
R002	2mΩ

5 Tolerance on rated resistance

F	±1%
J	±5%

6 Packaging form

TP	Paper taping
TE	Embossed taping

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 2/19

3. Rating

3.1 The ratings shall be in accordance with Table-1.

3.1.1 RLP series

Table-1(1)

	Dated discipation		Temperature		Rated resistance	Tolerance on rated								
Style	Rated dissipation (W)	Rated current (A)	resistance	(10 ⁻⁶ /°C)	$(m\Omega)$	resistance								
		0.4	K	100										
51.516	0.00	8.1	N	±70	5	-								
RLP16	0.33		K	100										
		5.7	N	±70	10									
			K	100										
		15.8	N	±70	2									
			K	100										
		11.1	N	±70	4									
			K	100										
		10.0	N	±70	5									
			K											
RLP20	0.5	9.1		100	6									
			N	±70										
		7.9	K	100	8									
			N	±70	Ů									
		7.4	K	100	9									
		7.1	N	±70	•									
		7.0	K	100	10									
		7.0	N	±70	10									
		31.6	-(Standard)	±150	1 2 3									
		01.0	K	±100										
		22.3	K	±100										
		22.3	N	±70		F(±1%) J(±5%)								
		10.0	K	±100										
		18.2	N	±70										
		15.8	K	±100	- 4									
		15.8	N	±70										
		14.1	K	±100	5									
			N	±70										
		12.9	K	±100	- 6									
			N	±70										
											44.0	K	±100	_
		11.9	N	±70	7									
DI Doo	1.0	4-	44.4	K	±100	0								
RLP32		11.1	N	±70	- 8									
		40.5	K	±100	_	1								
		10.5	N	±70	9									
			K	±100	46									
		10	N	±70	10									
			K	±100	44									
		9.5	N	±70	11									
		_	K	±100										
		9.1	N	±70	12									
		_	K	±100										
		8.7	N	±70	13									
			K	±100										
		8.4	N	±70	14									
			K	±100										
		8.1	N N		15									
			IN	±70										

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 3/19

Table-1(2)

Style	Rated dissipation (W)	Rated current (A)	Temperature of resistance	coefficient of	Rated resistance (mΩ)	Tolerance on rated resistance
		44.7	-(Standard)	±150	, ,	
	2.0		K	±100	1	
			N	±70		
		22.3	K	±100	2	
		22.3	Ν	±70	2	
		18.2	K	±100	3	
		10.2	N	±70	3	
		15.8	K	±100	4	
		15.8	Ν	±70	4	F(±1%) J(±5%)
	1.0	14.1	K	±100	5	
			N	±70	3	
		12.9	K	±100	6	
RLP63			N	±70	U	
			K	±100	7	
			N	±70	,	
		11.1	K	±100	8	
			N	±70	O .	
		10.5	K	±100	9	
			N	±70	3	
		9.1	K	±100	10	
			N	±70	10	
			K	±100	12	
			N	±70	12	
		8.1	K	±100	15	
		0.1	N	±70	10	

3.1.2 MLP series

Table-1(3)

			rabie-i (3)		
Style	Rated dissipation	Rated current	Temperature coefficient of		Rated resistance	Tolerance on rated
Style	(W)	(A)	resistance	(10 ⁻⁶ / °C)	$(m\Omega)$	resistance
MLP20	1.0	10	K	100	10	
IVILI 20	1.0	10	N	±70	10	
		31.6	K	100	2	
		31.0	N	±70	2	
		25.8	K	100	3	
		23.0	N	±70	S	F(±1%) J(±5%)
		22.3 20	K	100	4	
	2.0		N	±70	4	
			K	100	5	
			N	±70	3	
MLP63		18.2	K	100	6	
WILL GO			N	±70	U	
		16.9	K	100	7	
			N	±70	'	
		15.8	K	100	8	
		10.0	N	±70	U	
		14.9	K	100	9	
			N	±70	J	
		14.1	K	100	10	
		17.1	N	±70	10	

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 4/19

Style	Insulation voltage (V)	Category temperature range (°C)
RLP10		
RLP16		
RLP20		
RLP32	100	<i>–</i> 55∼+155
RLP63		
MLP20		
MLP63		

3.2 Climatic category

55/155/56 Lower category temperature –55 °C

Upper category temperature +155 °C

Duration of the damp heat, steady state test 56days

3.3 Stability class

5% Limits for change of resistance:

-for long-term tests ±5%

-for short-term tests ±1%

3.4 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

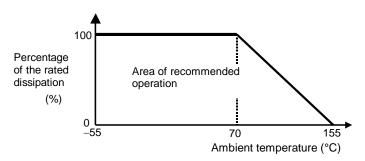


Figure-1 Derating curve

3.5 Rated voltage

d.c. or a.c. r.m.s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

E: Rated voltage (V)

P: Rated dissipation (W)

R: Rated resistance (
$$\Omega$$
)

3.6 Rated current

The rated current calculated from the square root of the quotient of the rated resistance and the rated dissipation.

I: Rated current (A)
$$I = \sqrt{P / R}$$
P: Rated dissipation (W)
R: Rated resistance (Ω)

The rated current shall be corresponding to rated voltage.

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 5/19

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units	Application
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RLP16, 20, 32, MLP20
TE	Embossed taping	12mm width, 4mm pitches	4,000 pcs.	RLP63, MLP63

5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.

5.1.1 RLP series

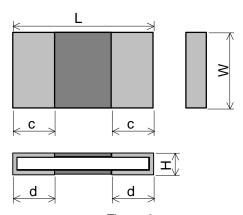
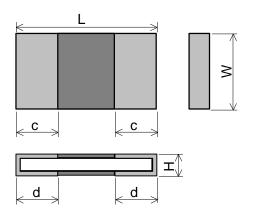


Figure-2

Table–3(1) Unit: mm

	Table-3(T)					Offil. Iffili
Style	Rated resistance (m Ω)	L	W	Н	С	d
RLP16	5	1.6±0.1	0.8±0.1	0.35±0.10	0.2±0.1	0.6±0.1
IXLF 10	10	1.0±0.1	0.0±0.1	0.3±0.1	0.2±0.1	0.3±0.1
	2			0.22±0.10	0.35±0.10	0.55±0.20
	4			0.35±0.10	0.35±0.10	0.75±0.20
	5			0.35±0.10	0.35±0.10	0.6±0.2
RLP20	6	2.0±0.15	1.25±0.15	0.35±0.10	0.35±0.10 0.35±0.10 0.35±0.10 0.35±0.10 1.1±0.25 0.5±0.25 0.7±0.25 1.1±0.25 1.0±0.25 0.85±0.25	0.47±0.20
	8			0.22±0.10	0.35±0.10	0.6±0.2
	9			0.22±0.10	0.35±0.10 0.4 1.1±0.25 1.7 0.5±0.25 0.5	0.52±0.20
	10			0.22±0.10		0.47±0.20
	1			0.32±0.15	1.1±0.25	1.1±0.25
	2			0.32±0.15	0.5±0.25	0.5±0.25
	3			0.35±0.10	0.7±0.25	1.3±0.25
	4			0.35±0.10	1.1±0.25	1.1±0.25
	5			0.35±0.10	1.0±0.25	1.0±0.25
	6			0.35±0.10	0.85±0.25	0.85±0.25
	7]	1	0.35±0.10	0.7±0.25
RLP32	8	3.2±0.15	1.6±0.15	0.35±0.10	0.6±0.25	0.6±0.25
	9	0.2_0		0.3±0.1	0.75±0.25	0.75±0.25
	10			0.28±0.10	0.5±0.25	0.5±0.25
	11			0.28±0.10	0.5±0.25	0.5±0.25
	12			0.22±0.10	0.65±0.25	0.65±0.25
	13			0.22±0.10	0.65±0.25	0.65±0.25
	14			0.22±0.10	0.55±0.25	0.55±0.25
	15			0.22±0.10	0.5±0.25	0.5±0.25

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 6/19



		Tal	ole-3(2)			Unit: mm
Style	Rated resistance (m Ω)	L	W	Н	С	d
	1		3.2±0.25	0.38±0.15	2.2±0.25	2.2±0.25
	2			0.38±0.15	1.1±0.25	1.1±0.25
	3			0.45±0.15	2.2±0.25	2.2±0.25
	4			0.35±0.15	2.2±0.25	2.2±0.25
	5			0.34±0.15	1.95±0.25	1.95±0.25
DI Dea	6	6.3±0.25		0.34±0.15	1.75±0.25	1.75±0.25
RLP63	7	0.3±0.25	3.1±0.25	0.35±0.15	1.4±0.25	1.4±0.25
	8			0.35±0.15	1.1±0.25	1.1±0.25
	9			0.35±0.15	0.8±0.25	0.8±0.25
	10			0.23±0.15	1.75±0.25	1.75±0.25
	12			0.23±0.15	1.4±0.25	1.4±0.25
	15			0.23±0.15	0.05±0.25	0 05±0 25

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 7/19

5.1.2 MLP series

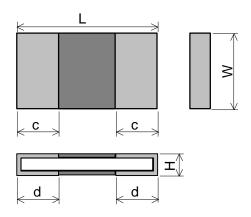


Table-3(3)

Unit: mm

Style	Rated resistance (m Ω)	L	W	Н	С	d
MLP20	10	2.0±0.15	1.25±0.15	0.22±0.10	0.33±0.15	0.47±0.20
	2			0.58±0.15	2.2±0.25	2.2±0.25
	3			0.45±0.15	2.2±0.25	2.2±0.25
	4			0.34±0.15	2.2±0.25	2.2±0.25
	5		3.1±0.25	0.51±0.15	1.1±0.25	1.1±0.25
MLP63	6	6.3±0.25		0.5±0.15	1.1±0.25	1.1±0.25
	7			0.5±0.15	0.6±0.25	0.6±0.25
	8			0.35±0.15	1.1±0.25	1.1±0.25
	9			0.35±0.15	0.8±0.25	0.8±0.25
	10			0.35±0.15	0.5±0.25	0.5±0.25

5.2 Net weight (Reference)

<u> </u>							
Style	Rated resistance (m Ω)	Net weight (mg)					
RLP16	5,10	2					
RLP20	2, 4 to 6 , 8 to 10	3					
RLP32	1 to 3	12					
NLF32	4 to 15	11					
RLP63	1,2	47					
KLF03	3 to 10,12 15	43					
MLP20	10	3					
MLP63	2 to 10	60					

6. Marking

The Rated resistance of RLP16 should not be marked standard.

6.1 RLP63, MLP63

The rated resistance shall be marked in 4 characters consisting of 3 figures and a letter and marked on over coat side.

(Example) "R010" \rightarrow 0.01 [Ω] \rightarrow 10 [m Ω]

"1L50" \rightarrow 0.0015 [Ω] \rightarrow 1.5 [m Ω]

6.2 RLP20, 32, MLP20

The rated resistance shall be marked in combination of two figures and underlines and marked on over coat side.

(Example) " $\underline{05}$ " \rightarrow 0.005 [Ω] \rightarrow 5 [m Ω]

" $\underline{10}$ " \rightarrow 0.01 [Ω] \rightarrow 10 [m Ω]

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 8/19

7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

No.	Test items		rable-4 Condition of test (` '	01_1)		Performance requirements
1	Visual examination	Sub-claus	`	010 0 02	01 1)		As in 4.4.1
'	Visual examination		e 4.4. i iy visual examina		The marking shall be legible, as		
		Crieckeub	y visuai examina		checked by visual examination.		
2	Dimension	Sub-claus	e 4 4 2				As specified in Table-3 of this
-	Zimenelen	Cub clade	0 1. 1.2				specification.
	Resistance	Resistance	value shall be	measure	ed bv m	ountina	As in 4.5.2
			te of the following			3	The resistance value shall
			b + a				correspond with the rated
		Current	Curr				resistance taking into account the
		terminal	term	inal	٦.		specified tolerance.
		Vo	voltage terminal		☐:Copper ☐:Solder		
			mage terrinia.		_		
			Resistance		Uni	t:mm	
		Style	value(m Ω)	а	b	С	
			5	0.6	0.8		
		RLP16	10,	1.0	0.6	0.9	
			2	0.5	1.1		
		RLP20	4 to 6, 8 to 10	0.8	1 1 1	1.36	
			1	1.0	1.45		
			2	2.1	0.9		
		RLP32	3	0.8	1.55	1.7	
		KLF3Z	4	1.0	1.45	1.7	
			5 and 6	1.4	1.25		
			7 to 15	2.1	0.9		
			1	1.5	3.0	4.0	
			2	4.0	1.8		
		RLP63	3, 4	1.8	2.9	3.5	
			5	2.4	2.6		
		MLP20	6 to 10,12,15 10	4.0 0.8	1.8 0.95	1.36	
			2 to 4	1.8	2.9		
		MLP63	5 to 10	4.0	1.8	3.5	
		Thickness of copper clad: 0.035mm 4-Terminal method					
	Measurement current: 1(A)						
			measuring appa	aratus co	ding to		
	DC Low-ohm Mater (1A) of AX-1152D for ADEX						
		CORPORATION.					

METAL-PLATE CHIP RESISTOR; LOW OHM

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 9/19

Table-4(2)

No	Test items	Condition of toot (IIS C 5201 1)	Performance requirements
		Condition of test (JIS C 5201–1)	Performance requirements
3	Voltage proof	Sub-clause 4.7	No breakdown or flash over
		Method: 4.6.1.4(See Figure–5)	
		Test voltage: Alternating voltage with a peak value	
		of 1.42 times the insulation voltage.	
		Duration: 60 s±5 s	D 400
		Insulation resistance	R≥1 GΩ
		Test voltage: Insulation voltage	
		Duration: 1 min.	
4	Solderability	Sub-clause 4.17	As in 4.17.4.5
		Without aging	The terminations shall be covered
		Flux: The resistors shall be immersed in a	with a smooth and bright solder
		non-activated soldering flux for 2 s.	coating.
		Bath temperature: 235 °C±5 °C	
		Immersion time: 2 s±0.5 s	
5	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: RLP16: Figure–3–1	
	Overload	RLP20, MLP20 Figure-3-2	
	(in the mounted state)	RLP32 Figure-3-3	
		RLP63, MLP63 Figure-3-4	
		Sub-clause 4.13	
		The applied voltage shall be 2.5 times the rated	
		voltage or the current corresponding to.	
		Duration: 2 s	
		Visual examination	No visible damage
		Resistance	ΔR ≤ ±1%
	Solvent resistance of the	Sub-clause 4.30	Legible marking
	marking	Solvent: 2-propanol	
		Solvent temperature: 23 °C±5 °C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure 4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 3mm(RLP16, 20, 32, MLP20)	
		1 mm(RLP63, MLP63)	
		Resistance	ΔR ≤ ±1%
	Final measurements	Sub-clause 4.33.6	
		Visual examination	No visible damage
	I	viodai onai i ii iadoi i	

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 10/19

Table-4(3)

	Table-4(3)								
No	Test	t item	S	Condition of test (JIS C 5201-1)	Performance requirements				
7	Resistance heat	to	soldering	Sub-clause 4.18 (JEITA RC-2144 2.3.2) Substrate material: Epoxide woven glass Test substrate: Figure-3-1 T1:Pre-heat minimum temp.:150±5 °C T2:Pre-heat maximum temp.:180±5 °C T3:Soldering temp.:220 °C T4:Peak temp.:260 °C t1:Pre-heat duration:120±5 s t2:Soldering duration:60 to 90 s t3:Peak duration(T4-5°C):20 to 40 s Pre-reflow soldering: 1 time (Initial measurements) Reflow soldering: 3 times T4 T3 T2 T1					
	Component resistance		solvent	Visual examination Resistance Sub-clause 4.29 Solvent: 2-propanol Solvent temperature: 23 °C±5 °C Method 2 Recovery: 48 h Visual examination Resistance	No visible damage $ \Delta R \leq \pm 1\% $ No visible damage $ \Delta R \leq \pm 1\% $				
8	Mounting Adhesion			Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3-1 Sub-clause 4.32 Force: 5 N Duration: 10 s±1 s	No visible damage				
	Rapid chang	je tem	nperature	Visual examination Sub-clause 4.19 Lower category temperature:-55 °C Upper category temperature:+155 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles. Visual examination Resistance	No visible damage $\Delta R \le \pm 1\%$				

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 11/19

Table-4(4)

	1able-4(4)								
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements						
9	Climatic sequence	Sub-clause 4.23							
	-Dry heat	Sub-clause 4.23.2							
		Test temperature: +155 °C							
		Duration: 16 h							
	–Damp heat, cycle	Sub-clause 4.23.3							
	(12+12hour cycle)	Test method: 2							
	First cycle	Test temperature: 55 °C							
		[Severity(2)]							
	-Cold	Sub-clause 4.23.4							
		Test temperature –55 °C							
		Duration: 2h							
	–Damp heat, cycle	Sub-clause 4.23.6							
	(12+12hour cycle)	Test method: 2							
	Remaining cycle	Test temperature: 55 °C							
		[Severity (2)]							
		Number of cycles: 5 cycles							
	–D.C. load	Sub-clause 4.23.7							
		The applied current shall be the rated current.							
		Duration: 1 min.	No visible damage						
		Visual examination	$\Delta R \le \pm 5\%$						
		Resistance	A(\(\sigma\) 10 /0						
10	Mounting	Sub-clause 4.31							
		Substrate material: Epoxide woven glass							
		Test substrate: RLP16: Figure–3–1							
		RLP20, MLP20 Figure-3-2							
		RLP32 Figure–3–3							
	F. I	RLP63, MLP63 Figure-3-4							
	Endurance at 70 °C	Sub-clause 4.25.1							
		Ambient temperature: 70 °C±2 °C							
		Duration: 1000 h							
		The current shall be applied in cycles of 1.5 h on							
		and 0.5 h.							
		The applied current shall be the rated current							
		Examination at 48 h, 500 h and							
		1000 h:	No visible damage						
		Visual examination	$\Delta R \le \pm 5\%$						
		Resistance	△11 ≥ ±0 /0						
11	Mounting	Sub-clause 4.31							
		Substrate material: Epoxide woven glass							
	Manieties of maintains 20	Test substrate: Figure–3–1							
	Variation of resistance with	Sub-clause 4.8	As in Table–1						
	temperature	+20 °C / +155 °C							

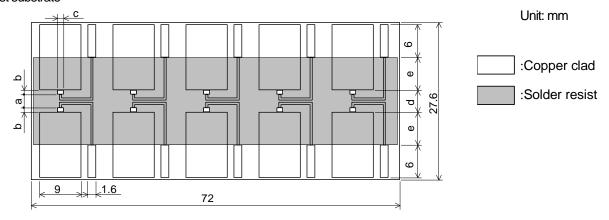
RLP10, 16, 20, 32, 63, MLP20, 63 Page: 12/19

Table-4(5)

		(-)	
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
12	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3-1	
	Damp heat, steady state	Sub-clause 4.24 Ambient temperature: 40 °C±2 °C Relative humidity: 93 ½ % Without current applied. Visual examination Resistance	No visible damage Legible marking ∆R ≤ ±5%
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table-4
	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass	
	Endurance at upper category temperature	Test substrate: Figure–3–1 Sub–clause 4.25.3 Ambient temperature:155 °C±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h:	
		Visual examination Resistance	No visible damage ΔR ≤ ±5%

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 13/19

8. Test substrate



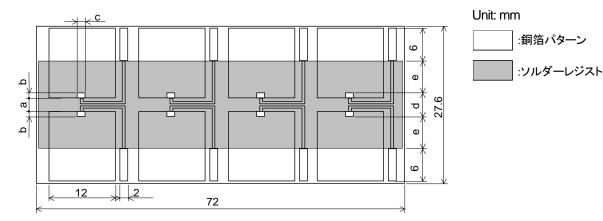
Style	Rated resistance (m Ω)	а	b	С	d	е
RLP16	5	0.6	0.9	0.9	2.2	6.2
KLP10	10	1.0	0.6	0.9	2.2	0.2
RLP20	2	0.5	1.1	1.26	2.7	E 0E
KLP20	4 to 6, 8 to 10	8.0	0.95	1.36	2.7	5.95
	1	1.0	1.45			
	2	2.1	0.9		3.9	5.35
חו חממ	3	8.0	1.55	17		
RLP32	4	1.0	1.45	1.7		
	5 and 6	1.4	1.25			
	7 to 15	2.1	0.9			
	1	1.5	3.05			
	2	4.0	1.8			
RLP63	3, 4	1.8	2.9	3.5	7.6	3.5
	5	2.4	2.6			
	6 to 10,12,15	4.0	1.8			
MLP20	10	0.8	0.95	1.36	2.7	5.95
MLDG2	2 to 4	1.8	2.9	2.5	76	2.5
MLP63	5 to 10	4.0	1.8	3.5	7.6	3.5

Figure-3-1 RLP, MLP TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 14/19

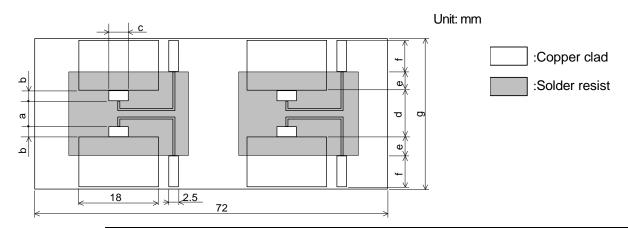


Style	Rated resistance (m Ω)	а	b	С	d	е
RLP20	2	0.5	1.1			
KLP20	4 to 6, 8 to 10	0.8	0.95	1.36	2.7	5.95
MLP20	10	0.8	0.95			

Figure-3-2 RLP20, MLP20 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm



Style	Rated resistance (m Ω)	а	b	С	d	е	f	g
	1	1.0	1.45				11.68	39
	2	2.1	0.9				6.0	27.6
RLP32	3	0.8	1.55	1.7	3.9	5.35	0.0	21.0
KLF32	4	1.0	1.45	1.7	3.9	5.33	11.68	39
	5 and 6	1.4	1.25				6.0	27.6
	7 to 15	2.1	0.9				6.0	27.6

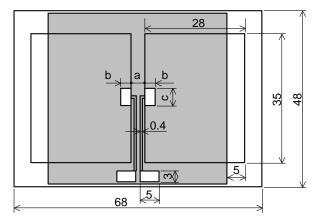
Figure-3-3 RLP32, MLP32 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.07mm

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 15/19



Unit: mm							
:Copper clad							
:Solder resist							
Style	Rated resistance $(m\Omega)$	а	b	С			
	1	2.0	3.0	4.0			
	2	4.0	1.8				
RLP63	3, 4	1.8	2.9	2.5			
	5	2.4	2.6	3.5			
	6 to 10,12,15	4.0	1.8				
MLP63	2 to 4	1.8	2.9	3.5			
IVILPOS	5 to 10	4.0	1.8	3.3			

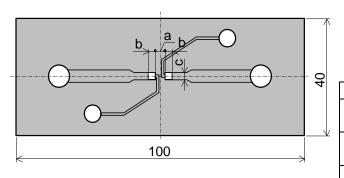
Figure-3-4 RLP63, MLP63 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.07mm

Remark: In the case of connection by connector, the connecting terminals are gold plated.

However, the plating is not necessary when the connection is made by soldering.

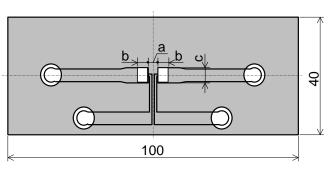


Unit: mm		
	:Copper clad	
	:Solder resist	

Style	Rated resistance (m Ω)	а	b	С
RLP16	5	0.6	0.9	0.0
	10	1.0	0.6	0.9
RLP20	2,3	0.5	1.1	1 26
	4 to 6, 8 to 10	0.8	0.95	1.36
RLP32	1	1.0	1.45	
	2	2.1	0.9	
	3	8.0	1.55	1.7
	4	1.0	1.45	1.7
	5 and 6	1.4	1.25	
	7 to 15	2.1	0.9	
MLP20	10	0.8	0.95	1.36

RLP, MLP BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 16/19



Unit: mm		
	:Copper clad	
	:Solder resist	

Style	Rated resistance (m Ω)	а	b	С
RLP63	1	1.5	3.05	4.0
	2	4.0	1.8	3.5
	3, 4	1.8	2.9	
	5	2.4	2.6	
	6 to 10,12,15	4.0	1.8	
MLP63	2 to 4	1.8	2.9	3.5
	5 to 10	4.0	1.8	3.5

RLP 63, MLP63 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

Figure-4

Remark. Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm

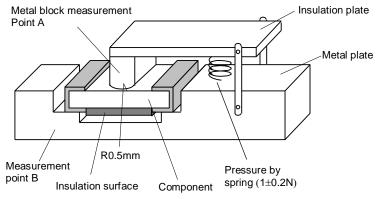


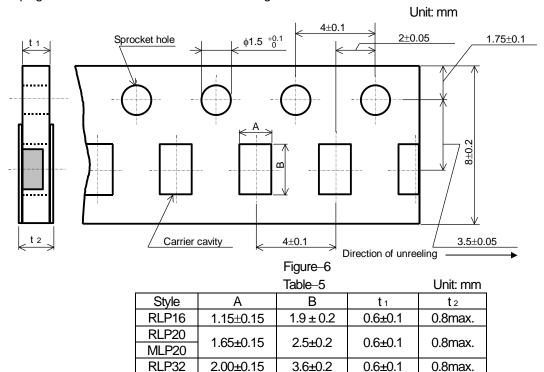
Figure-5

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 17/19

9. Taping

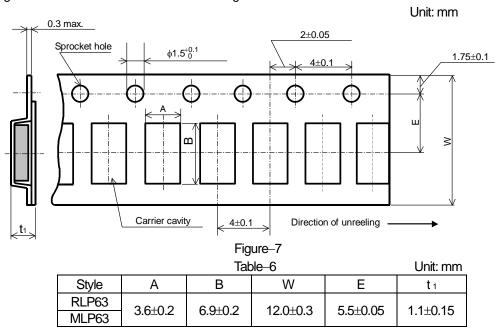
- 9.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010
- 9.2 Taping dimensions
- 9.2.1 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-5.



9.2.2 Embossed taping (12mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-7 and Table-6.



Title: METAL-PLATE CHIP RESISTOR; LOW OHM RLP10. 16. 20. 32. 63. MLP20. 63

- RLP10, 16, 20, 32, 63, MLP20, 63 Page: 18/19
- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following RLP16, 20, 32, MLP20: Figure–8, RLP63, MLP63: Figure–9.
- 6). When the tape is bent with the minimum radius for (RLP16, 20, 32, MLP20: 25mm, RLP63, MLP63: 30mm) the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.
 The maximum number of missing components shall be one or 0.1%, whichever is greater.

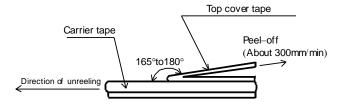


Figure-8

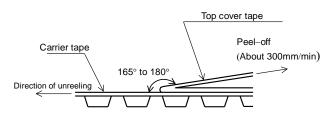
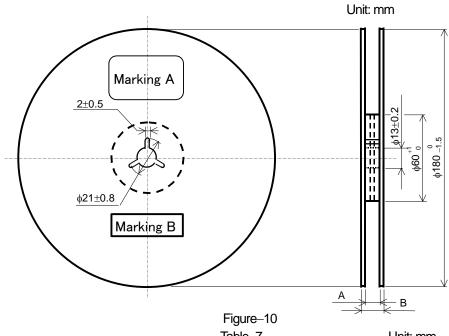


Figure-9

RLP10, 16, 20, 32, 63, MLP20, 63 Page: 19/19

9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure-10 and Table-7. Plastic reel (Based on EIAJ ET-7200C)



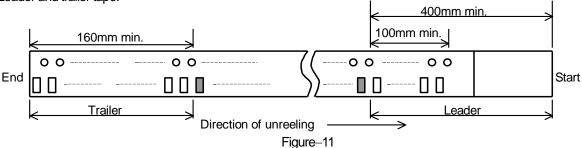
1 19410 10		
Table-7		Unit: mm
Α	В	Note
9 +1.0	11.4±1.0	Injection molding
	13 ± 1 0	\/acuum forming

Vacuum forming

17±1.0

13 +1.0 Note: Marking label shall be marked on a place of Marking A or two place of Marking A and B.

9.4 Leader and trailer tape.



10. Marking on package

The label of a minimum package shall be legibly marked with follows.

Style

RLP16, 20, 32, MLP20 RLP63, MLP63

10.1 Marking A

(1) Classification

(Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)

(2) Lot number (3) Quantity (4) Manufacturer's name or trade mark (5) Others

10.2 Marking B (KAMAYA Control label)